

DAC715

16-BIT DIGITAL-TO-ANALOG CONVERTER with 16-Bit Bus Interface

FEATURES

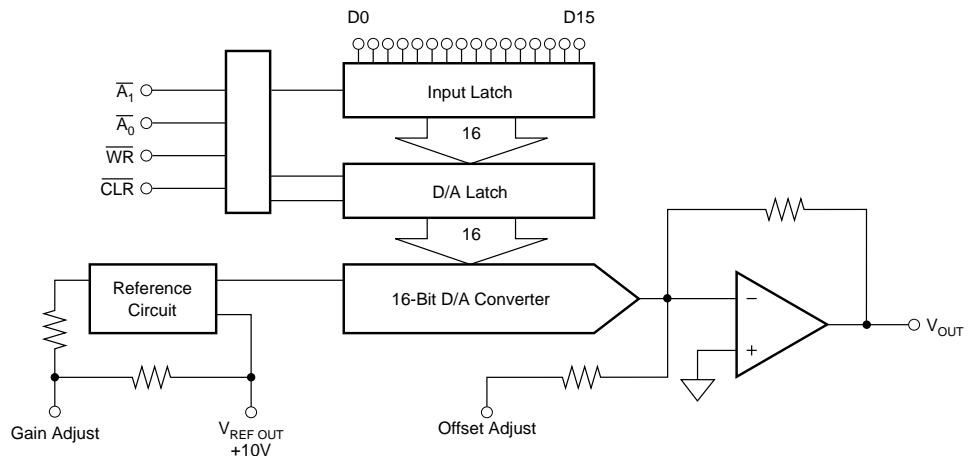
- HIGH-SPEED 16-BIT PARALLEL DOUBLE-BUFFERED INTERFACE
- VOLTAGE OUTPUT: 0 to +10V
- 13-, 14-, 15-BIT LINEARITY GRADES
- 16-BIT MONOTONIC OVER TEMPERATURE (L GRADE)
- POWER DISSIPATION: 600mW max
- GAIN AND OFFSET ADJUST: Convenient for Auto-Cal D/A Converters
- 28-LEAD DIP AND SOIC PACKAGES

DESCRIPTION

The DAC715 is a complete monolithic digital-to-analog converter including a +10V temperature compensated reference, current-to-voltage amplifier, 16-bit parallel interface that is double buffered, and an asynchronous clear function which immediately sets the output voltage to one-half of full-scale.

The output voltage range is 0 to +10V while operating from $\pm 12V$ or $\pm 15V$ supplies. The gain and bipolar offset adjustments are designed so that they can be set via external potentiometers or external D/A converters. The output amplifier is protected against short circuit to ground.

The 28-pin DAC715 is available in a 0.3" plastic DIP and wide-body plastic SOIC package. The DAC715P, U, PB, and UB are specified over the -40°C to $+85^{\circ}\text{C}$ temperature range while the DAC715PK, UK, PL, and UL are specified over the 0°C to $+70^{\circ}\text{C}$ range.



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SPECIFICATIONS

ELECTRICAL

At $T_A = +25^\circ\text{C}$, $V_{CC} = \pm 15\text{V}$, and after a 10-minute warm-up, unless otherwise noted.

| PARAMETER | DAC715P, U | | | DAC715PB, UB | | | DAC715PK, UK | | | DAC715PL, UL | | | UNITS |
|--|------------|------------|------------------|------------------------|-----|-----|--------------|-----|-----|--------------|-----|-----|--------------------------|
| | MIN | TYP | MAX | MIN | TYP | MAX | MIN | TYP | MAX | MIN | TYP | MAX | |
| INPUT | | | | | | | | | | | | | |
| RESOLUTION | | | | | | | | | | | | | |
| DIGITAL INPUTS | | | | | | | | | | | | | |
| Input Code | | | | | | | | | | | | | |
| Logic Levels ⁽¹⁾ : V_{IH} | | | | | | | | | | | | | |
| V_{IH} | +2.0 | Binary | Two's Complement | | | | | | | | | | |
| V_{IL} | 0 | | | +V _{CC} - 1.4 | * | * | * | * | * | * | * | * | V |
| I_{IH} ($V_i = +2.7\text{V}$) | | | | +0.8 | * | * | * | * | * | * | * | * | μA |
| I_{IL} ($V_i = +0.4\text{V}$) | | | | ±10 | * | * | * | * | * | * | * | * | μA |
| TRANSFER CHARACTERISTICS | | | | | | | | | | | | | |
| ACCURACY | | | | | | | | | | | | | |
| Linearity Error | | | | | | | | | | | | | |
| T_{MIN} to T_{MAX} | | | | ±4 | | | ±2 | | | ±2 | | | LSB |
| Differential Linearity Error | | | | ±8 | | | ±4 | | | ±2 | | | LSB |
| T_{MIN} to T_{MAX} | | | | ±4 | | | ±2 | | | ±2 | | | LSB |
| Monotonicity Over Temp | | | | ±8 | | | ±4 | | | ±2 | | | LSB |
| Gain Error ⁽³⁾ | | | | ±0.1 | | | ±0.1 | | | 16 | | | Bits |
| T_{MIN} to T_{MAX} | | | | ±0.2 | | | ±0.15 | | | | | | % |
| Offset Error ⁽³⁾ | | | | ±0.1 | * | * | * | * | * | | | | % |
| T_{MIN} to T_{MAX} | | | | ±0.2 | * | * | * | * | * | | | | % FSR ⁽²⁾ |
| Power Supply Sensitivity Of Full Scale | | | | ±0.003 | * | * | * | * | * | | | | % FSR |
| | | | | ±30 | | | | | | | | | PPM FSR/%V _{CC} |
| DYNAMIC PERFORMANCE | | | | | | | | | | | | | |
| Settling Time (to ±0.003%FSR, 5kΩ II 500pF Load) ⁽⁴⁾ | | | | | | | | | | | | | |
| 10V Output Step | 6 | | 10 | | * | * | | * | * | | * | * | μs |
| 1 LSB Output Step ⁽⁵⁾ | 4 | | | | * | * | | * | * | | * | * | μs |
| Output Slew Rate | 10 | | | | * | * | | * | * | | * | * | V/μs |
| Total Harmonic Distortion + Noise | | | | | | | | | | | | | |
| 0dB, 1001Hz, $f_S = 100\text{kHz}$ | 0.005 | | | | * | * | | * | * | | * | * | % |
| -20dB, 1001Hz, $f_S = 100\text{kHz}$ | 0.03 | | | | * | * | | * | * | | * | * | % |
| -60dB, 1001Hz, $f_S = 100\text{kHz}$ | 3.0 | | | | * | * | | * | * | | * | * | % |
| SINAD | | | | | | | | | | | | | |
| 1001Hz, $f_S = 100\text{kHz}$ | 87 | | | | * | * | | * | * | | * | * | dB |
| Digital Feedthrough ⁽⁵⁾ | 2 | | | | * | * | | * | * | | * | * | nV-s |
| Digital-to-Analog Glitch Impulse ⁽⁵⁾ | 15 | | | | * | * | | * | * | | * | * | nV-s |
| Output Noise Voltage (includes Reference) | 120 | | | | * | * | | * | * | | * | * | nV/√Hz |
| ANALOG OUTPUT | | | | | | | | | | | | | |
| Output Voltage Range | 0 to +10 | | | | * | * | | * | * | | * | * | V |
| +V _{CC} , -V _{CC} = ±11.4V | ±5 | | | 0.1 | * | * | | * | * | | * | * | mA |
| Output Current | | | | | | | | | | | | | Ω |
| Output Impedance | | | | | | | | | | | | | |
| Short Circuit to ACOM | | | | | | | | | | | | | |
| Duration | | | | Indefinite | | | | | | | | | |
| REFERENCE VOLTAGE | | | | | | | | | | | | | |
| Voltage | +9.975 | +10.000 | +10.025 | | * | * | * | * | * | * | * | * | V |
| T _{MIN} to T _{MAX} | +9.960 | 1 | +10.040 | | * | * | * | * | * | * | * | * | V |
| Output Resistance | | | | | * | * | | * | * | | * | * | Ω |
| Source Current | | | | | * | * | | * | * | | * | * | mA |
| Short Circuit to ACOM, Duration | 2 | Indefinite | | | | | | | | | | | |
| POWER SUPPLY REQUIREMENTS | | | | | | | | | | | | | |
| Voltage: +V _{CC} | +11.4 | +15 | +16.5 | | * | * | * | * | * | * | * | * | V |
| -V _{CC} | -16.5 | -15 | -11.4 | | * | * | * | * | * | * | * | * | V |
| Current (no load, ±15V Supplies) | | | | | * | * | * | * | * | | * | * | |
| +V _{CC} | 13 | 15 | 25 | | * | * | * | * | * | | * | * | mA |
| -V _{CC} | 22 | 25 | 600 | | * | * | * | * | * | | * | * | mW |
| Power Dissipation | 525 | | | | * | * | * | * | * | | * | * | |
| TEMPERATURE RANGE | | | | | | | | | | | | | |
| Specification All Grades | | | | | | | | | | | | | |
| Storage | -40 | -60 | | | * | * | | * | 0 | | * | * | °C |
| Thermal Resistance θ_{JA} | | | | | | | | | | | | | °C/W |
| DIP Package | 75 | | | | * | * | | * | * | | * | * | °C/W |
| SOIC Package | 75 | | | | * | * | | * | * | | * | * | °C/W |

* Specifications are the same as grade to the left.

NOTES: (1) Digital inputs are TTL and +5V CMOS compatible over the specification temperature range. (2) FSR means Full Scale Range. For example, for a 0 to +10V output, FSR = 10V.

(3) Errors externally adjustable to zero. (4) Maximum represents greater than the 3σ limit. Not 100% tested for this parameter. (5) For the worst case code changes: FFFF_H to 0000_H and 0000_H to FFFF_H. These are Binary Two's Complement (BTC) codes. (6) Typical supply voltages times maximum currents.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| | |
|---|----------------------------|
| +V _{CC} to COMMON | 0V, +17V |
| -V _{CC} to COMMON | 0V, -17V |
| +V _{CC} to -V _{CC} | 34V |
| Digital Inputs to COMMON | -1V to +V _{CC} |
| External Voltage Applied to BPO and Range Resistors | ±V _{CC} |
| V _{REF OUT} | Indefinite Short to COMMON |
| V _{OUT} | Indefinite Short to COMMON |
| Power Dissipation | 750mW |
| Storage Temperature | -60°C to +150°C |
| Lead Temperature (soldering, 10s) | +300°C |

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

PACKAGE INFORMATION

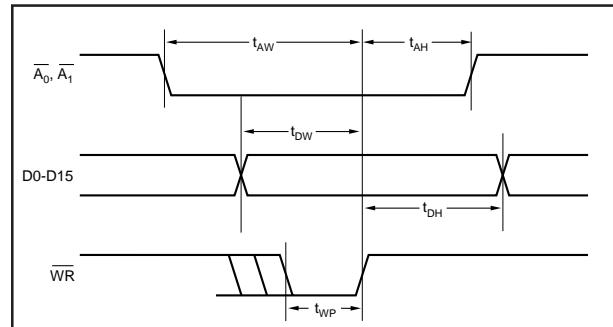
| PRODUCT | PACKAGE | PACKAGE DRAWING NUMBER ⁽¹⁾ |
|----------|--------------|---------------------------------------|
| DAC715P | Plastic DIP | 246 |
| DAC715U | Plastic SOIC | 217 |
| DAC715PB | Plastic DIP | 246 |
| DAC715UB | Plastic SOIC | 217 |
| DAC715PK | Plastic DIP | 246 |
| DAC715UK | Plastic SOIC | 217 |
| DAC715PL | Plastic DIP | 246 |
| DAC715UL | Plastic SOIC | 217 |

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ORDERING INFORMATION

| PRODUCT | PACKAGE | TEMPERATURE RANGE | DIFFERENTIAL LINEARITY ERROR MAX at +25°C |
|----------|--------------|-------------------|---|
| DAC715P | Plastic DIP | -40°C to +85°C | ±4LSB |
| DAC715U | Plastic SOIC | -40°C to +85°C | ±4LSB |
| DAC715PB | Plastic DIP | -40°C to +85°C | ±2LSB |
| DAC715UB | Plastic SOIC | -40°C to +85°C | ±2LSB |
| DAC715PK | Plastic DIP | 0°C to 70°C | ±2LSB |
| DAC715UK | Plastic SOIC | 0°C to 70°C | ±2LSB |
| DAC715PL | Plastic DIP | 0°C to 70°C | ±1LSB |
| DAC715UL | Plastic SOIC | 0°C to 70°C | ±1LSB |

TIMING DIAGRAM



TIMING SPECIFICATIONS

| $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $+V_{CC} = +12\text{V}$ or $+15\text{V}$, $-V_{CC} = -12\text{V}$ or -15V . | | | | |
|--|--|-----|-----|-------|
| SYMBOL | PARAMETER | MIN | MAX | UNITS |
| t_{DW} | Data Valid to End of WR | 50 | | ns |
| t_{AW} | \overline{A}_0 , \overline{A}_1 Valid to End of WR | 50 | | ns |
| t_{AH} | \overline{A}_0 , \overline{A}_1 Hold after End of WR | 10 | | ns |
| t_{DH} | Data Hold after end of WR | 10 | | ns |
| $t_{WP}^{(1)}$ | Write Pulse Width | 50 | | ns |
| t_{CP} | CLEAR Pulse Width | 200 | | ns |

NOTES: (1) For single-buffered operation, t_{WP} is 80ns min. Refer to page 10.

TRUTH TABLE

| \overline{A}_0 | \overline{A}_1 | \overline{WR} | \overline{CLR} | DESCRIPTION |
|------------------|------------------|-----------------|------------------|---------------------|
| 0 | 1 | 1 → 0 → 1 | 1 | Load Input Latch |
| 1 | 0 | 1 → 0 → 1 | 1 | Load D/A Latch |
| 1 | 1 | 1 → 0 → 1 | 1 | No Change |
| 0 | 0 | 0 | 1 | Latches Transparent |
| X | X | 1 | 1 | No Change |
| X | X | X | 0 | Reset D/A Latch |

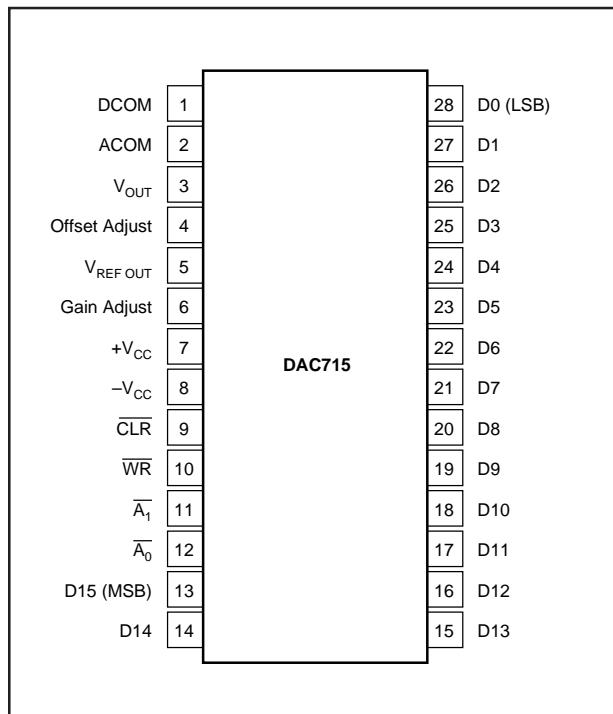
ELECTROSTATIC DISCHARGE SENSITIVITY

Electrostatic discharge can cause damage ranging from performance degradation to complete device failure. Burr-Brown Corporation recommends that all integrated circuits be handled and stored using appropriate ESD protection methods.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet published specifications.

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PIN CONFIGURATION

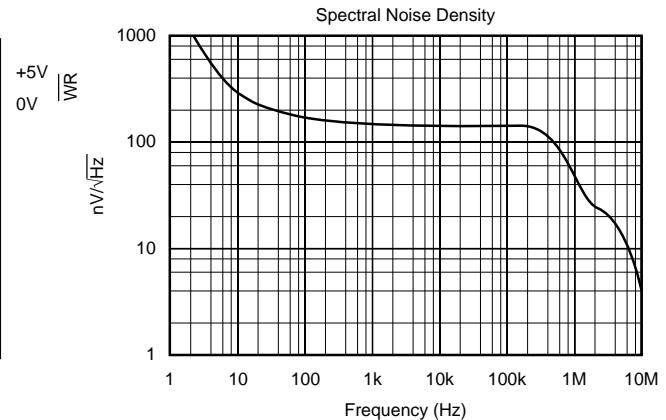
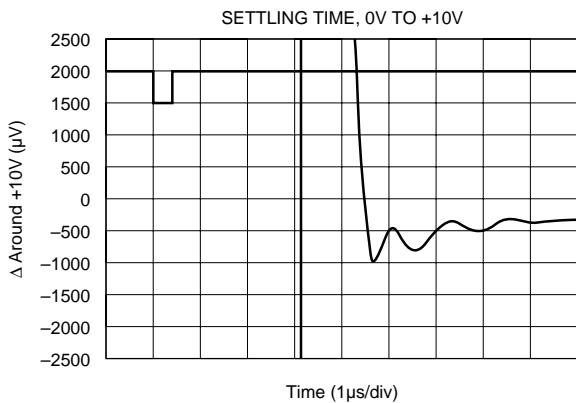
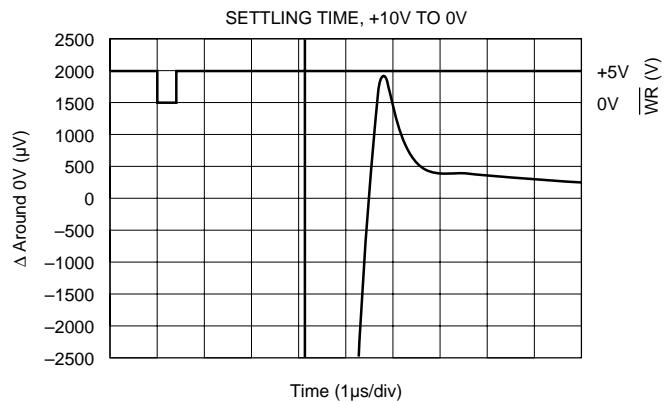
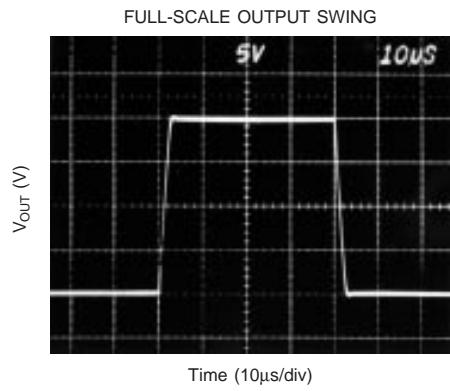
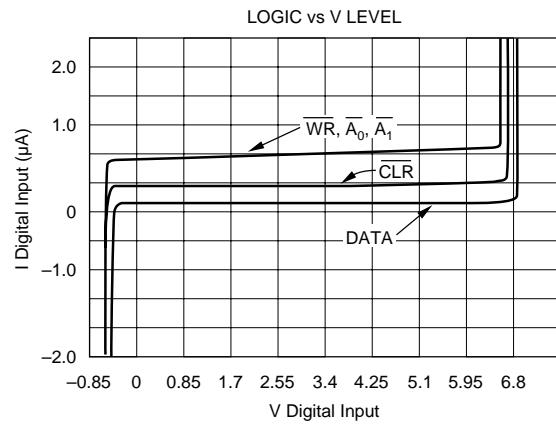
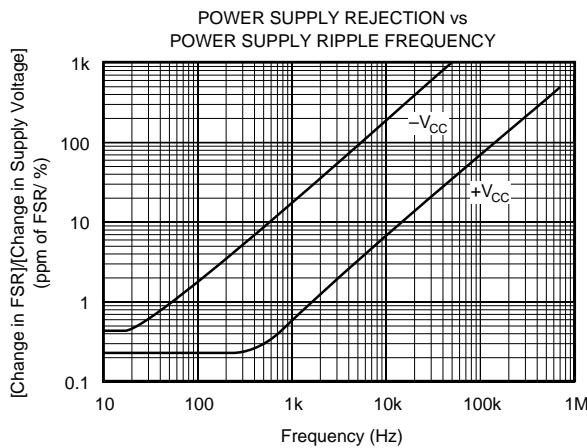


PIN DESCRIPTIONS

| PIN | LABEL | DESCRIPTION |
|-----|----------------------|---|
| 1 | DCOM | Digital Ground |
| 2 | ACOM | Analog Ground |
| 3 | V _{OUT} | 0 to +10V D/A Output |
| 4 | Offset Adjust | Offset Adjust |
| 5 | V _{REF OUT} | Voltage Reference Output |
| 6 | Gain Adjust | Gain Adjust |
| 7 | +V _{CC} | +12V to +15V Supply |
| 8 | -V _{CC} | -12V to -15V Supply |
| 9 | CLR | CLEAR. Sets D/A output to Half Scale (Active Low) |
| 10 | WR | Write (Active Low) |
| 11 | A ₁ | Enable for D/A latch (Active Low) |
| 12 | A ₀ | Enable for Input latch (Active Low) |
| 13 | D15 | Data Bit 15 (Most Significant Bit) |
| 14 | D14 | Data Bit 14 |
| 15 | D13 | Data Bit 13 |
| 16 | D12 | Data Bit 12 |
| 17 | D11 | Data Bit 11 |
| 18 | D10 | Data Bit 10 |
| 19 | D9 | Data Bit 9 |
| 20 | D8 | Data Bit 8 |
| 21 | D7 | Data Bit 7 |
| 22 | D6 | Data Bit 6 |
| 23 | D5 | Data Bit 5 |
| 24 | D4 | Data Bit 4 |
| 25 | D3 | Data Bit 3 |
| 26 | D2 | Data Bit 2 |
| 27 | D1 | Data Bit 1 |
| 28 | D0 | Data Bit 0 (Least Significant Bit) |

TYPICAL PERFORMANCE CURVES

At $T_A = +25^\circ\text{C}$, and $V_{CC} = \pm 15\text{V}$, unless otherwise noted.



DISCUSSION OF SPECIFICATIONS

LINEARITY ERROR

Linearity error is defined as the deviation of the analog output from a straight line drawn between the end points of the transfer characteristic.

DIFFERENTIAL LINEARITY ERROR

Differential linearity error (DLE) is the deviation from 1LSB of an output change from one adjacent state to the next. A DLE specification of $\pm 1/2$ LSB means that the output step size can range from 1/2LSB to 3/2LSB when the digital input code changes from one code word to the adjacent code word. If the DLE is more positive than -1LSB, the D/A is said to be monotonic.

MONOTONICITY

A D/A converter is monotonic if the output either increases or remains the same for increasing digital input values. Monotonicity of DAC715 is guaranteed over the specification temperature range to 13-, 14-, 15-, and 16-bits for performance grades DAC715P/U, DAC715PB/UB, DAC715PK/UK, and DAC715PL/UL respectively.

SETTLING TIME

Settling time is the total time (including slew time) for the D/A output to settle to within an error band around its final value after a change in input. Settling times are specified to within $\pm 0.003\%$ of Full Scale Range (FSR) for an output step change of 10V and 1LSB. The 1LSB change is measured at the Major Carry ($FFFF_H$ to 0000_H , and 0000_H to $FFFF_H$: BTC codes), the input transition at which worst-case settling time occurs.

TOTAL HARMONIC DISTORTION

Total harmonic distortion is defined as the ratio of the square root of the sum of the squares of the values of the harmonics to the value of the fundamental frequency. It is expressed in % of the fundamental frequency amplitude at sampling rate f_s .

SIGNAL-TO-NOISE AND DISTORTION RATIO (SINAD)

SINAD includes all the harmonic and outstanding spurious components in the definition of output noise power in addition to quantizing and internal random noise power. SINAD is expressed in dB at a specified input frequency and sampling rate, f_s .

DIGITAL-TO-ANALOG GLITCH IMPULSE

The amount of charge injected into the analog output from the digital inputs when the inputs change state. It is measured at half scale at the input codes where as many as possible switches change state—from $FFFF_H$ to 0000_H .

DIGITAL FEEDTHROUGH

When the D/A is not selected, high frequency logic activity on the digital inputs is coupled through the device and shows up as output noise. This noise is digital feedthrough.

OPERATION

The DAC715 is a monolithic integrated-circuit 16-bit D/A converter complete with 16-bit D/A switches and ladder network, voltage reference, output amplifier and microprocessor bus interface.

INTERFACE LOGIC

The DAC715 has double-buffered data latches. The input data latch holds a 16-bit data word before loading it into the second latch, the D/A latch. This double-buffered organization permits simultaneous update of several D/A converters. All digital control inputs are active low. Refer to the block diagram shown in Figure 1.

All latches are level-triggered. Data present when the enable inputs are logic "0" will enter the latch. When the enable inputs return to logic "1", the data is latched.

The \overline{CLR} input resets both the input latch and the D/A latch to give a half scale output.

LOGIC INPUT COMPATIBILITY

The DAC715 digital inputs are TTL compatible (1.4V switching level), low leakage, and high impedance. Thus the inputs are suitable for being driven by any type of 5V logic family, such as CMOS logic. An equivalent circuit for the digital inputs is shown in Figure 2.

The inputs will float to logic "0" if left unconnected. It is recommended that any unused inputs be connected to DCOM to improve noise immunity.

Digital inputs remain high impedance when power is off.

INPUT CODING

The DAC715 is designed to accept binary two's complement (BTC) input codes. For unipolar analog output configuration, a digital input of $7FFF_H$ gives a full scale output, 8000_H gives a zero output, and 0000_H gives half scale output.

INTERNAL REFERENCE

The DAC715 contains a +10V reference. The reference output may be used to drive external loads, sourcing up to 2mA. The load current should be constant, otherwise the gain of the converter will vary.

OUTPUT VOLTAGE SWING

The output amplifier of the DAC715 is committed to a 0 to +10V output range. It will provide a 0 to +10V output swing while operating on $\pm 11.4V$ or higher voltage supplies.

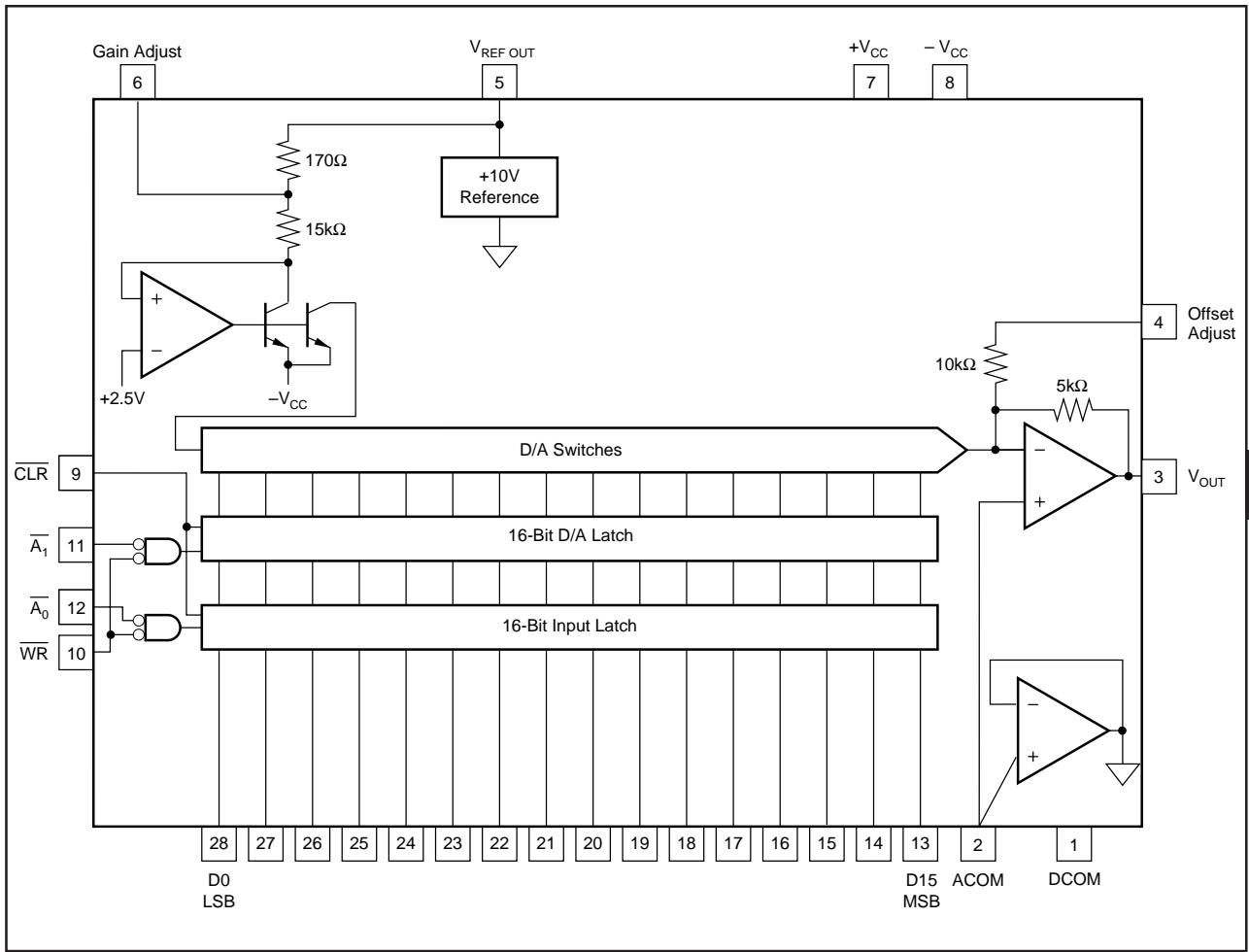


FIGURE 1. DAC715 Block Diagram.

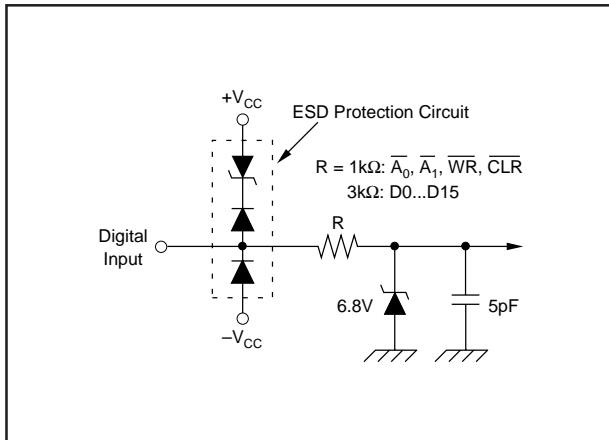


FIGURE 2. Equivalent Circuit of Digital Inputs.

GAIN AND OFFSET ADJUSTMENTS

Figure 3 illustrates the relationship of offset and gain adjustments for a unipolar connected D/A converter. Offset should be adjusted first to avoid interaction of adjustments. See Table I for calibration values and codes. These adjustments have a minimum range of $\pm 0.3\%$.

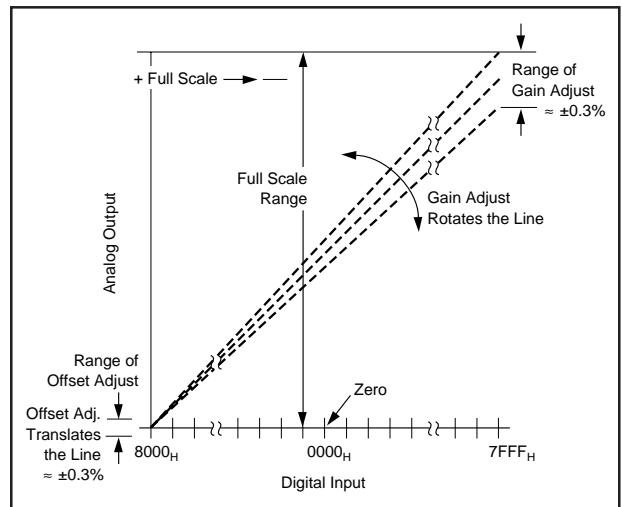


FIGURE 3. Relationship of Offset and Gain Adjustments.

Offset Adjustment

Apply the digital input code that produces zero output voltage and adjust the offset potentiometer or the offset adjust D/A converter for 0V.

| DAC715 CALIBRATION VALUES 1 LEAST SIGNIFICANT BIT = 152 μ V | | |
|--|-------------------------|-------------------|
| DIGITAL INPUT CODE BINARY TWO'S COMPLEMENT, BTC | ANALOG OUTPUT (V) | DESCRIPTION |
| 7FFF _H | 9.999847 | Full Scale -1LSB |
| 4000 _H | 7.5 | 3/4 Scale |
| 0001 _H | 5.000152 | Half Scale + 1LSB |
| 0000 _H | 5 | Half Scale |
| FFFF _H | 4.999847 | Half Scale - 1LSB |
| C000 _H | 2.5 | 1/4 Scale |
| 8000 _H | 0 | Zero |

TABLE I. Digital Input and Analog Output Voltage Calibration Values.

Gain Adjustment

Apply the digital input that gives the maximum positive voltage output. Adjust the gain potentiometer or the gain adjust D/A converter for this positive full scale voltage.

INSTALLATION

GENERAL CONSIDERATIONS

Due to the high-accuracy of the DAC715, system design problems such as grounding and contact resistance become very important. A 16-bit converter with a 10V full-scale range has a 1LSB value of 152 μ V. With a load current of 5mA, series wiring and connector resistance of only 60m Ω will cause a voltage drop of 300 μ V. To understand what this means in terms of a system layout, the resistivity of a typical 1 ounce copper-clad printed circuit board is 1/2 m Ω per square. For a 5mA load, a 10 milliinch wide printed circuit conductor 60 milliinches long will result in a voltage drop of 150 μ V.

The analog output of DAC715 has an LSB size of 152 μ V (–96dB). The noise floor of the D/A must remain below this level in the frequency range of interest. The DAC715's noise spectral density (which includes the noise contributed by the internal reference) is shown in the Typical Performance Curves section.

Wiring to high-resolution D/A converters should be routed to provide optimum isolation from sources of RFI and EMI. The key to elimination of RF radiation or pickup is small loop area. Signal leads and their return conductors should be kept close together such that they present a small capture cross-section for any external field. Wire-wrap construction is not recommended.

POWER SUPPLY AND REFERENCE CONNECTIONS

Power supply decoupling capacitors should be added as shown in Figure 4. Best performance occurs using a 1 to 10 μ F tantalum capacitor at $-V_{CC}$. Applications with less critical settling time may be able to use 0.01 μ F at $-V_{CC}$ as

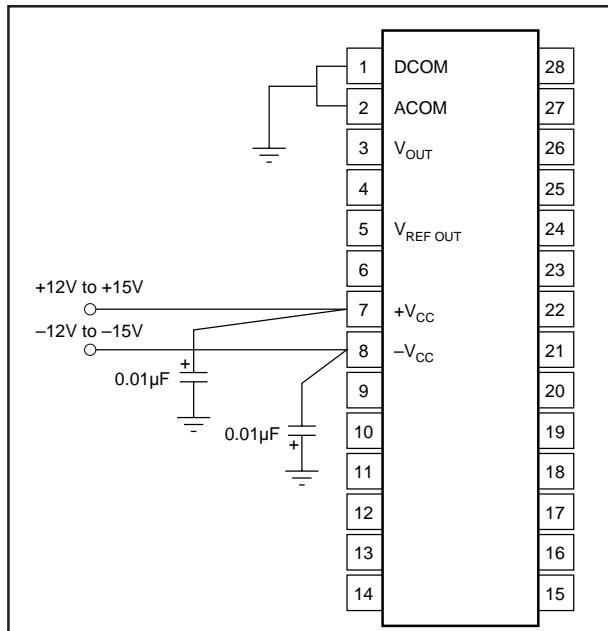


FIGURE 4. Power Supply Connections.

well as at $+V_{CC}$. The capacitors should be located close to the package.

The DAC715 has separate ANALOG COMMON and DIGITAL COMMON pins. The current through DCOM is mostly switching transients and are up to 1mA peak in amplitude. The current through ACOM is typically 5 μ A for all codes. Use separate analog and digital ground planes with a single interconnection point to minimize ground loops. The analog pins are located adjacent to each other to help isolate analog from digital signals. Analog signals should be routed as far as possible from digital signals and should cross them at right angles. A solid analog ground plane around the D/A package, as well as under it in the vicinity of the analog and power supply pins, will isolate the D/A from switching currents. It is recommended that DCOM and ACOM be connected directly to the ground planes under the package.

If several DAC715s are used or if DAC715 shares supplies with other components, connecting the ACOM and DCOM lines together once at the power supplies rather than at each chip may give better results.

LOAD CONNECTIONS

Since the reference point for V_{OUT} and $V_{REF OUT}$ is the ACOM pin, it is important to connect the D/A converter load directly to the ACOM pin. Refer to Figure 5.

Lead and contact resistances are represented by R_1 through R_3 . As long as the load resistance R_L is constant, R_1 simply introduces a gain error and can be removed by gain adjustment of the D/A or system-wide gain calibration. R_2 is part of R_L if the output voltage is sensed at ACOM.

In some applications it is impractical to return the load to the ACOM pin of the D/A converter. Sensing the output voltage at the SYSTEM GROUND point is reasonable, because there is no change in DAC715 ACOM current, provided that

R_3 is a low-resistance ground plane or conductor. In this case you may wish to connect DCOM to SYSTEM GROUND as well.

GAIN AND OFFSET ADJUST

Connections Using Potentiometers

GAIN and OFFSET adjust pins provide for trim using external potentiometers. 15-turn potentiometers provide sufficient resolution. Range of adjustment of these trims is at least $\pm 0.3\%$ of Full Scale Range. Refer to Figure 6.

Using D/A Converters

The GAIN ADJUST and OFFSET ADJUST circuits of the DAC715 have been arranged so that these points may be easily driven by external D/A converters. Refer to Figure 7. 12-bit D/A converters provide an OFFSET adjust resolution and a GAIN adjust resolution of $30\mu\text{V}$ to $50\mu\text{V}$ per LSB step.

Nominal values of GAIN and OFFSET occur when the D/A

converters outputs are at approximately half scale, 0V.

DIGITAL INTERFACE

BUS INTERFACE

The DAC715 has a 16-bit double-buffered data interface with control lines for easy connection to a 16-bit bus. The double-buffered feature permits update of several D/As simultaneously.

A_0 is the enable control for the DATA INPUT LATCH. A_1 is the enable for the D/A LATCH. WR is used to strobe data into latches enabled by A_0 , and A_1 . Refer to the block diagram of Figure 1 and to Timing Diagram on page 3.

CLR sets the INPUT DATA LATCH and D/A LATCH to 0000_H (5V at the D/A output).

SINGLE-BUFFERED OPERATION

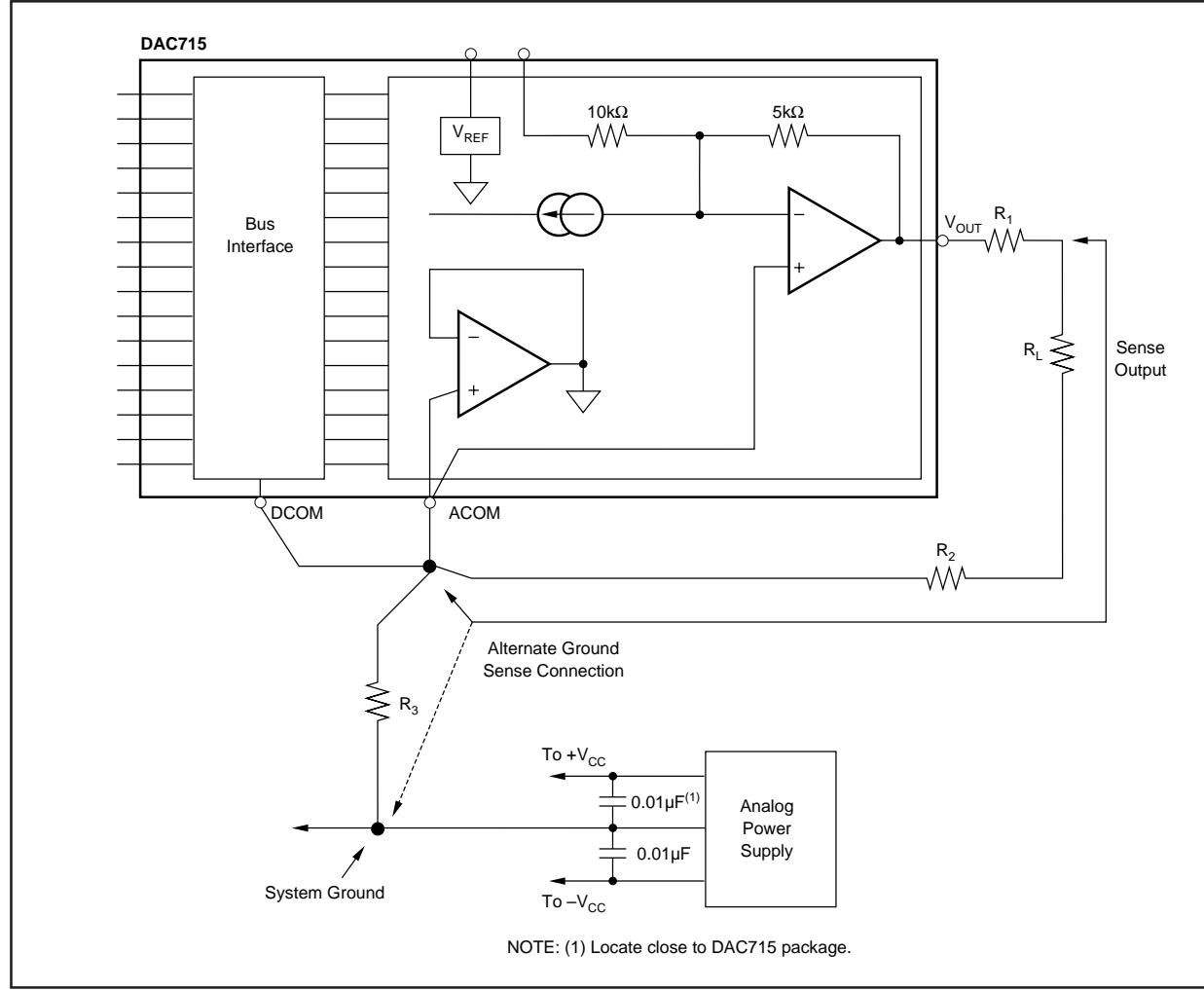


FIGURE 5. System Ground Considerations for High-Resolution D/A Converters.

To operate the DAC715 interface as a single-buffered latch, the DATA INPUT LATCH is permanently enabled by connecting A_0 to DCOM. If A_1 is not used to enable the D/A, it should be connected to DCOM also. For this mode of operation, the width of WR will need to be at least 80ns minimum to pass data through the DATA INPUT LATCH and into the D/A LATCH.

TRANSPARENT INTERFACE

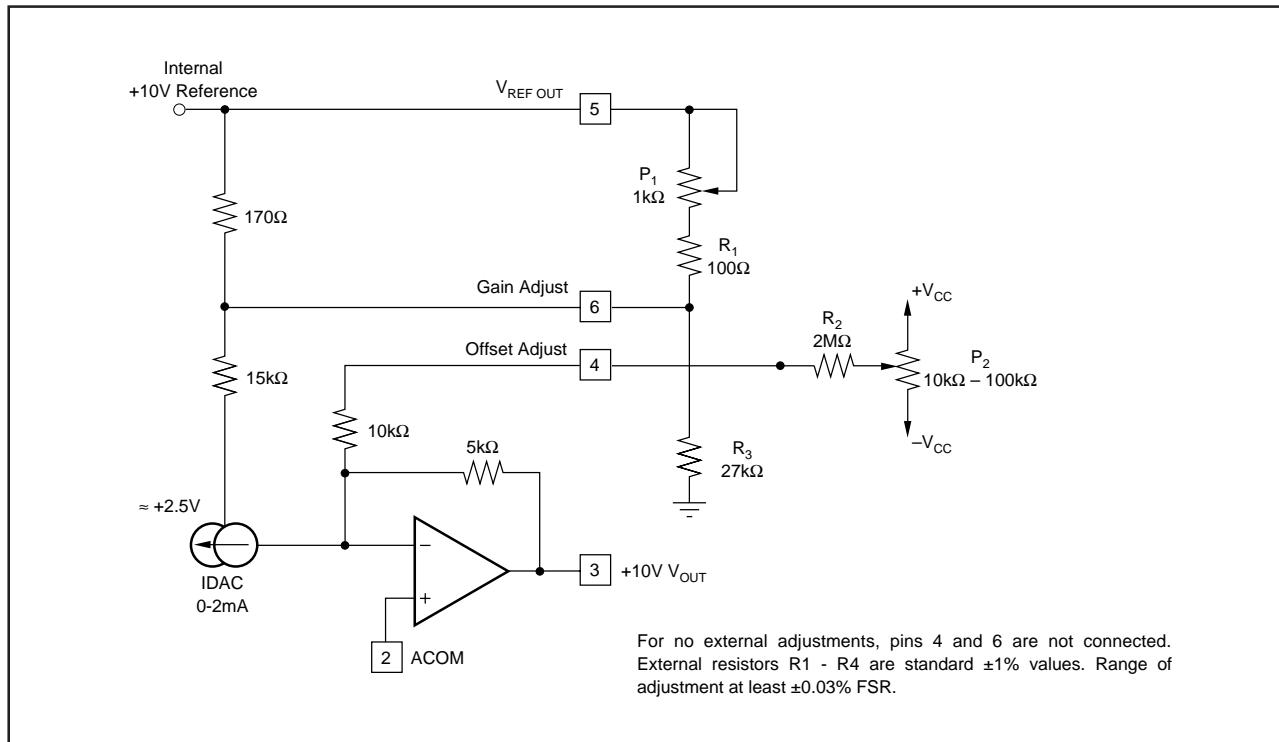


FIGURE 6. Manual Offset and Gain Adjust Circuits.

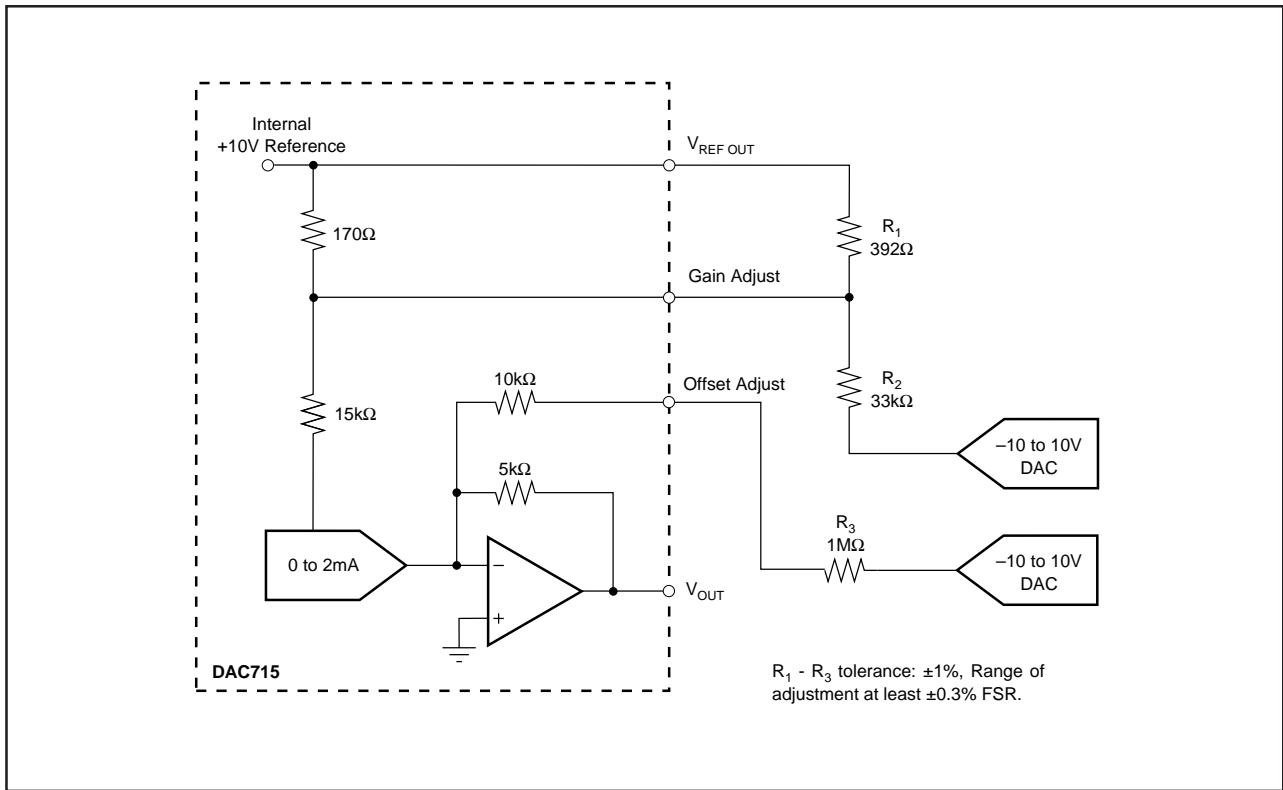


FIGURE 7. Gain and Offset Adjustment Using D/A Converters.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|---|
| DAC715P | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | DAC715P L | |
| DAC715PB | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | DAC715P B | |
| DAC715PBG4 | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | DAC715P B | |
| DAC715PG4 | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | DAC715P L | |
| DAC715PK | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | DAC715P K | |
| DAC715PKG4 | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | DAC715P K | |
| DAC715PL | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | DAC715P L | |
| DAC715PLG4 | LIFEBUY | PDIP | NT | 28 | 13 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | DAC715P L | |
| DAC715U | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | DAC715U | Samples |
| DAC715UB | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | DAC715U B | Samples |
| DAC715UK | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | 0 to 70 | DAC715U K | Samples |
| DAC715UKG4 | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | 0 to 70 | DAC715U K | Samples |
| DAC715UL | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | 0 to 70 | DAC715U L | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

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TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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